

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

1. (Currently Amended) A process for producing a printed wiring board, comprising: ~~a step of~~

depositing a base metal of nickel and chromium on at least one surface of an insulating film to form a base metal layer and depositing a conductive metal layer of copper or a copper alloy on a surface of the base metal layer ~~to form a conductive metal, thereby forming a surface metal layer; and a step of~~

~~selectively removing a the surface metal layer of a base film, which is formed through the above step, by etching with an etching solution containing at least one selected from ferric chloride, cupric chloride, and a mixture of sulfuric acid and hydrogen peroxide to form a wiring pattern, wherein;~~

~~after the metal layer of the base film is selectively removed by etching to form a wiring pattern, microetching is carried out, the surface metal layer with a solution containing potassium persulfate; and then,~~

~~treating the base metal layer is treated with an etching solution, which is capable of dissolving metal and has a function that it can passivate metal that is remaining in trace amounts, to dissolve and remove most of a metal that forms the base metal layer exposed between the wiring patterns and to passivate a trace amount of a residual metal which has not been dissolved by treatment with the etching solution containing at least one selected from a mixture of potassium permanganate and KOH, potassium bichromate, and a mixture of sodium permanganate and KOH.~~

2. (Cancelled)

3. (Original) The process for producing a printed wiring board as claimed in claim 1, wherein the conductive metal layer is obtained by depositing copper or a copper alloy by plating.

4. (Original) The process for producing a printed wiring board as claimed in claim 1, wherein after the metal layer of the base film is selectively removed by etching to form a wiring pattern, the surface of the wiring pattern formed by selectively etching the metal layer is subjected to pickling, and then the base metal layer is treated with a treating liquid capable of dissolving chromium and passivating an extremely slight amount of chromium which has not been dissolved.

5 - 11. (Cancelled)